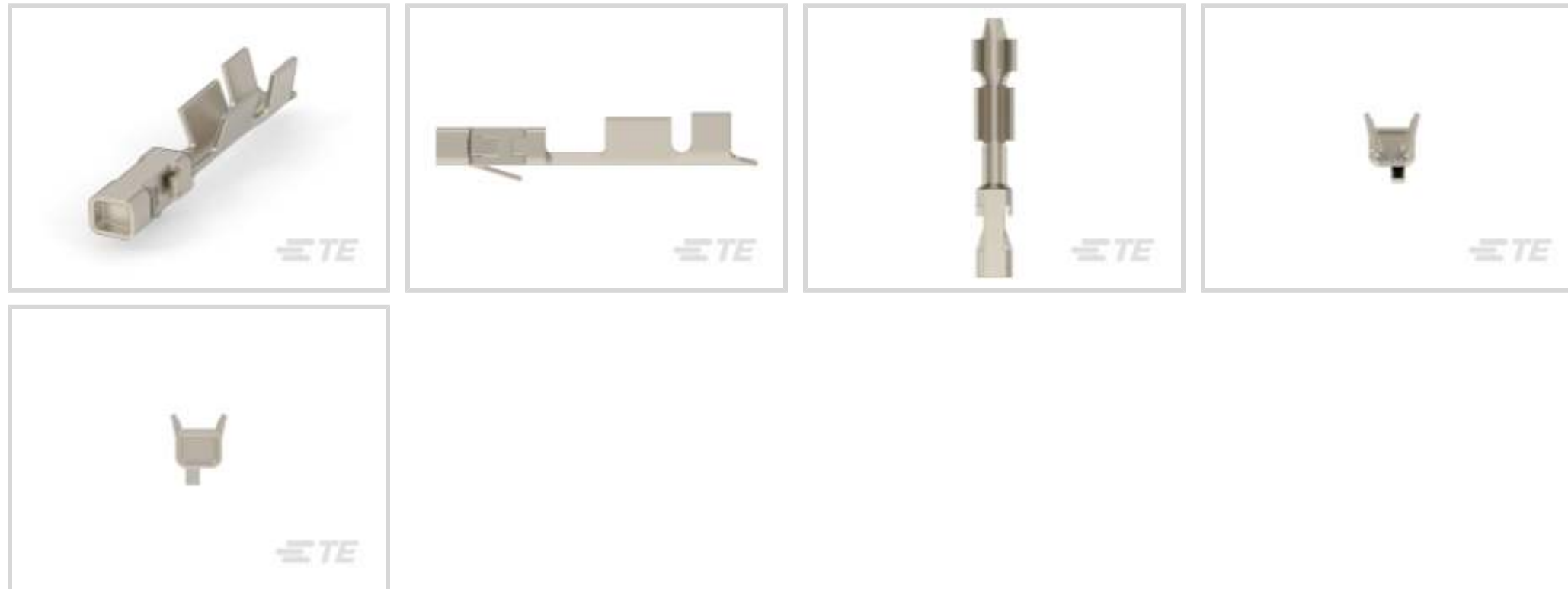




Connectors > PCB Connectors > Wire-to-Board Connectors > Wire-to-Board Connector Contacts



Contact Type: **Socket**

Connector System: **Wire-to-Board**

Wire Size: **.12 – .4 mm<sup>2</sup>**

## Features

### Product Type Features

|                                   |               |
|-----------------------------------|---------------|
| Applied Pressure                  | Intermediate  |
| Connector System                  | Wire-to-Board |
| Connector & Contact Terminates To | Wire & Cable  |

### Configuration Features

|                                   |               |
|-----------------------------------|---------------|
| Compatible With Wire & Cable Type | Discrete Wire |
|-----------------------------------|---------------|

### Electrical Characteristics

|                                       |         |
|---------------------------------------|---------|
| Termination Resistance                | 12 mΩ   |
| Insulation Resistance                 | 5000 MΩ |
| Dielectric Withstanding Voltage (Max) | 750 V   |
| Operating Voltage                     | 250 VAC |

### Contact Features

|  |                  |
|--|------------------|
| Mating Square Post Dimension                   | .64 mm [.025 in] |
| Wire Contact Termination Area Plating Material | Gold Flash       |
|  | 30 μin           |
| Contact Base Material                          | Beryllium Copper |



|                                      |        |
|--------------------------------------|--------|
| Contact Type                         | Socket |
| Contact Mating Area Plating Material | Gold   |
| Contact Current Rating (Max)         | 3 A    |

#### Termination Features

|                                    |       |
|------------------------------------|-------|
| Termination Method to Wire & Cable | Crimp |
|------------------------------------|-------|

#### Mechanical Attachment

|                         |      |
|-------------------------|------|
| Wire Insulation Support | With |
|-------------------------|------|

#### Dimensions

|                                      |                          |
|--------------------------------------|--------------------------|
| Compatible Insulation Diameter Range | 1.55 mm[.061 in]         |
| Wire Size                            | .12 – .4 mm <sup>2</sup> |

#### Usage Conditions

|                             |                            |
|-----------------------------|----------------------------|
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
|-----------------------------|----------------------------|

#### Operation/Application

|                     |                |
|---------------------|----------------|
| Circuit Application | Power & Signal |
|---------------------|----------------|

#### Industry Standards

|                    |                       |
|--------------------|-----------------------|
| Approved Standards | CSA LR7189, UL E28476 |
|--------------------|-----------------------|

#### Packaging Features

|                    |       |
|--------------------|-------|
| Packaging Quantity | 12500 |
| Packaging Method   | Reel  |

#### Other

|                            |   |
|----------------------------|---|
| Connector Contacts Comment | (*) For use with Model "K" machines. Call the Technical Assistance Center (1-800-522-6752) for any tooling questions. |
|----------------------------|---|

### Product Compliance

For compliance documentation, visit the product page on [TE.com](https://www.te.com)>

|   |   |
|---|---|
| EU RoHS Directive 2011/65/EU                  | Compliant   |
| EU ELV Directive 2000/53/EC                   | Compliant   |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold   |
| EU REACH Regulation (EC) No. 1907/2006        | Current ECHA Candidate List: JUNE 2023 (235)<br>Candidate List Declared Against: JUNE 2023 (235)<br>Does not contain REACH SVHC |



Halogen Content Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

Solder Process Capability Not applicable for solder process capability

Product Compliance Disclaimer

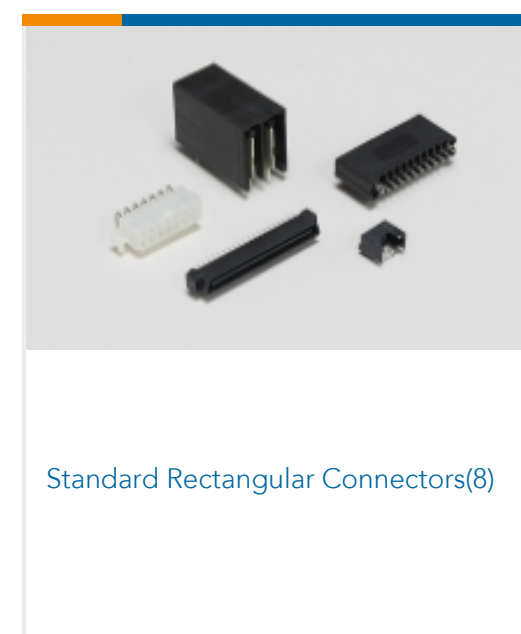
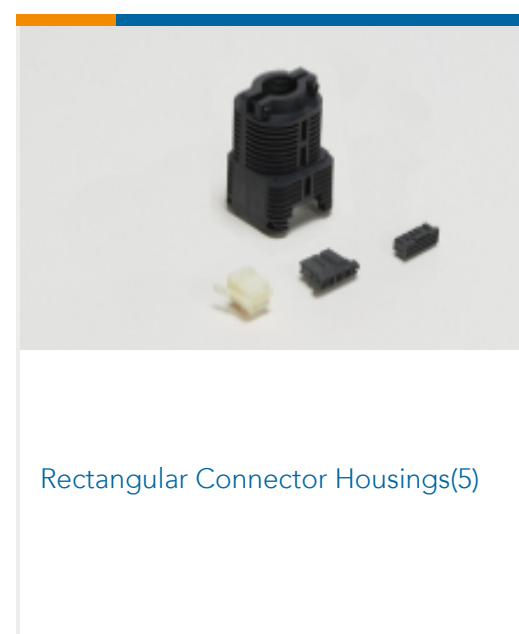
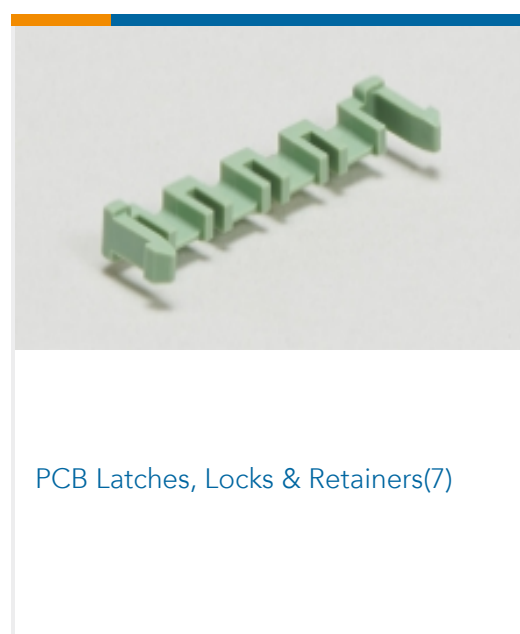
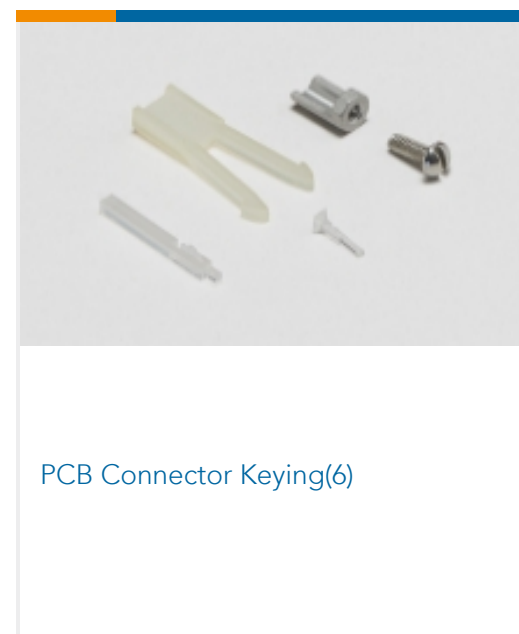
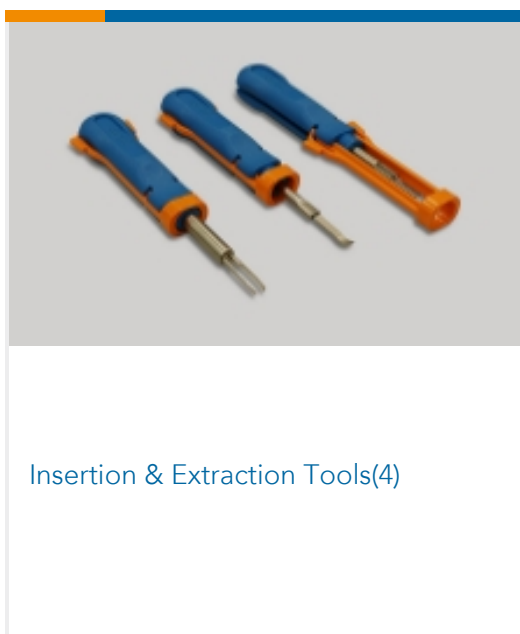
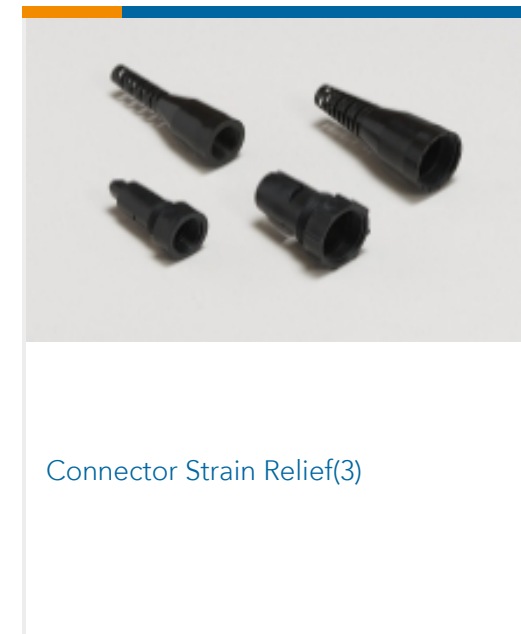
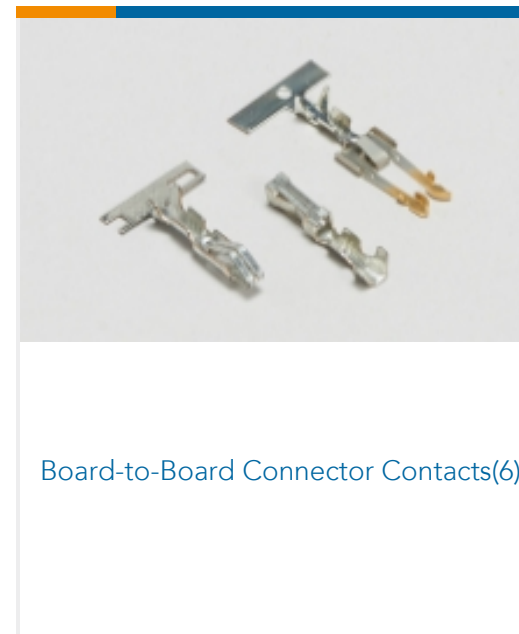
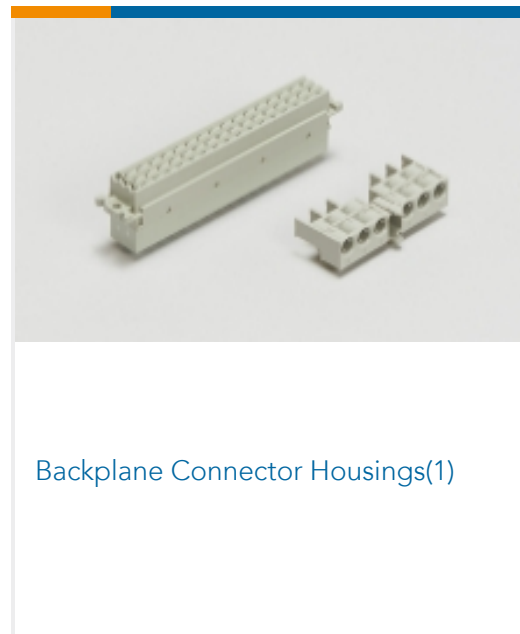
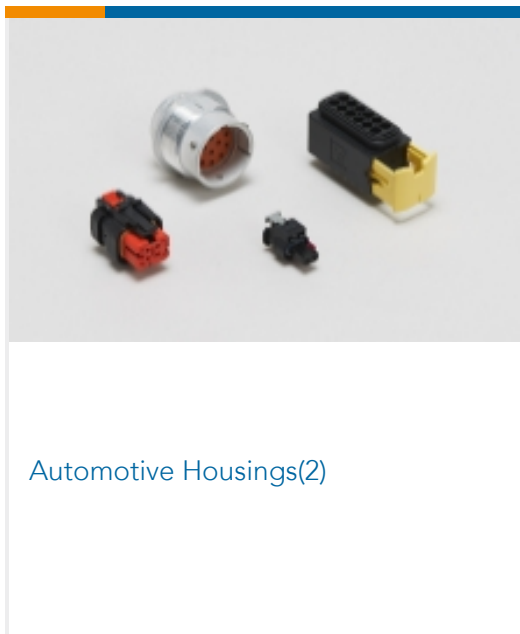
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

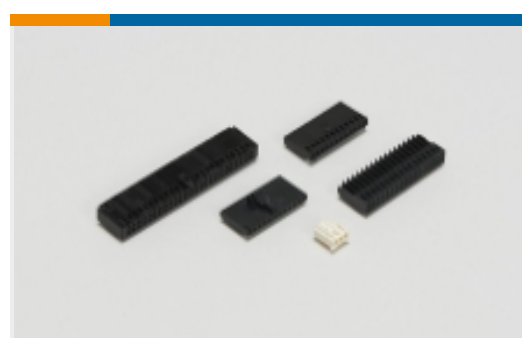
### Compatible Parts

|  |   |   |   |
|--|---|---|---|
|  <p>TE Part # 91517-1<br/>CCII FEMALE MOD IV REC 24-22 ASSY</p> |  <p>TE Part # 1-87499-7<br/>10 MODIV HSG SR MRKD .100CL</p>  |  <p>TE Part # 1-102387-2<br/>64 MODIV HSG COMP DR .100 POL</p> |  <p>TE Part # 1-87631-2<br/>16 MODIV HSG DR MRKD .100 POL</p>  |
|  <p>TE Part # 87499-7<br/>04 MODIV HSG SR MRKD .100CL</p>       |  <p>TE Part # 1-87456-5<br/>20 MODIV HSG COMP DR .100CL</p>  |  <p>TE Part # 1-87631-6<br/>20 MODIV HSG DR MRKD .100 POL</p>  |  <p>TE Part # 1-102387-0<br/>50 MODIV HSG COMP DR .100 POL</p> |
|  <p>TE Part # 87977-8<br/>20 MODIV HSG DR MRKD .100 POL</p>     |  <p>TE Part # 102387-5<br/>24 MODIV HSG COMP DR .100 POL</p> |  <p>TE Part # 102241-6<br/>08 MODIV HSG COMP SR .100 POL</p>   |  <p>TE Part # 87977-4<br/>12 MODIV HSG DR MRKD .100 POL</p>    |

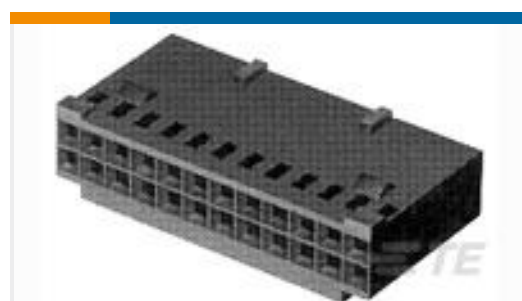
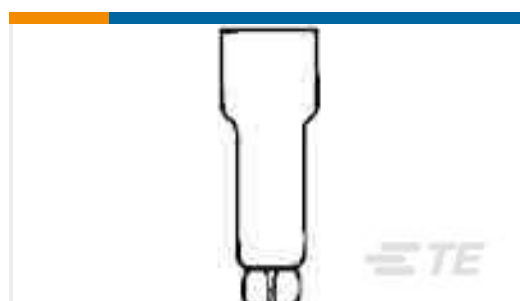
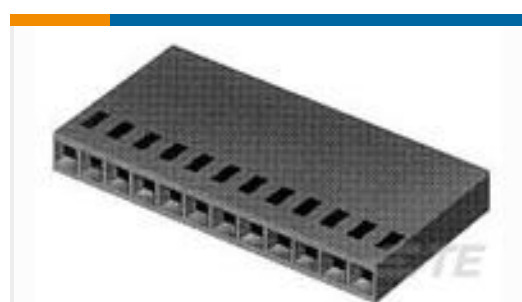
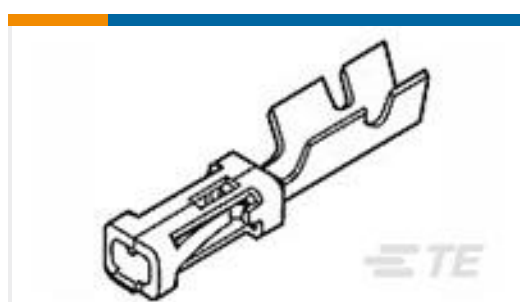
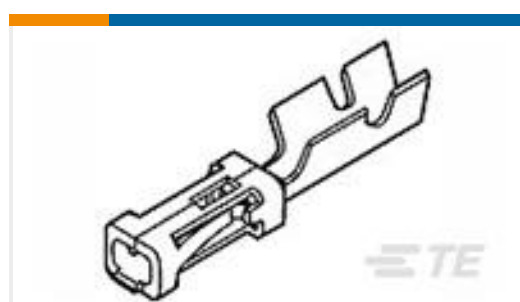


## Also in the Series | AMPMODU IV/V



Wire-to-Board Connector Assemblies  
& Housings(447)Wire-to-Board Connector Contacts  
(322)

## Customers Also Bought

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IDC LOW PRO HDR 40P VERT LG LATE Part #329251  
SPLICE, CE, 22-12TE Part #1-87631-0  
14 MODIV HSG DR MRKD .100 POLTE Part #1-87499-3  
08 MODIV HSG SR MRKD .100CLTE Part #87809-1  
MOD V RECP PLTD 30 AUTE Part #102918-1  
MOD IV RECP PLTD 30 SEL

## Documents

### Product Drawings

[MOD IV RECP PLTD 30 SEL](#)

English

### CAD Files

[3D PDF](#)

3D

Customer View Model

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**Product Specifications**

[Application Specification](#)

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**Product Environmental Compliance**

[TE Material Declaration](#)

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